

FDS6673BZ_F085

P-Channel PowerTrench® MOSFET

-30V, -14.5A, 7.8mΩ

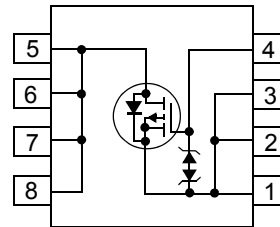
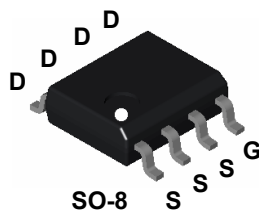
General Description

This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench process that has been especially tailored to minimize the on-state resistance.

This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.

Features

- Max $r_{DS(on)}$ = 7.8mΩ, $V_{GS} = -10V$, $I_D = -14.5A$
- Max $r_{DS(on)}$ = 12mΩ, $V_{GS} = -4.5V$, $I_D = -12A$
- Extended V_{GS} range (-25V) for battery applications
- HBM ESD protection level of 6.5kV typical (note 3)
- High performance trench technology for extremely low $r_{DS(on)}$
- High power and current handling capability
- RoHS compliant
- Qualified to AEC Q101



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	-30	V
V_{GS}	Gate to Source Voltage	± 25	V
I_D	Drain Current -Continuous (Note1a)	-14.5	A
	-Pulsed	-75	A
P_D	Power Dissipation for Single Operation (Note1a)	2.5	W
	(Note1b)	1.2	
	(Note1c)	1.0	
T_J, T_{STG}	Operating and Storage Temperature	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Note 1)	25	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDS6673BZ	FDS6673BZ_F085	13"	12mm	2500 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-30			V
$\frac{\Delta B_{VDSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		-20		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$			-1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 25\text{V}, V_{DS} = 0\text{V}$			± 10	μA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-1	-1.9	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		8.1		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = -10\text{V}, I_D = -14.5\text{A}$		6.5	7.8	m Ω
		$V_{GS} = -4.5\text{V}, I_D = -12\text{A}$		9.6	12	
		$V_{GS} = -10\text{V}, I_D = -14.5\text{A}$ $T_J = 125^\circ\text{C}$		9.7	12	
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{V}, I_D = -14.5\text{A}$		60		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$		3500	4700	pF
C_{oss}	Output Capacitance			600	800	pF
C_{rss}	Reverse Transfer Capacitance			600	900	pF

Switching Characteristics (Note 2)

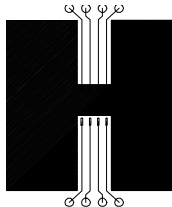
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -15\text{V}, I_D = -1\text{A}$ $V_{GS} = -10\text{V}, R_{GS} = 6\Omega$		14	26	ns
t_r	Rise Time			16	29	ns
$t_{d(off)}$	Turn-Off Delay Time			225	36	ns
t_f	Fall Time			105	167	ns
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -14.5\text{A}$		88	124	nC
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}, V_{GS} = -5\text{V}, I_D = -14.5\text{A}$		46	65	nC
Q_{gs}	Gate to Source Gate Charge			8		nC
Q_{gd}	Gate to Drain Charge			23.5		nC

Drain-Source Diode Characteristics

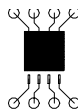
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -2.1\text{A}$		-0.7	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F = 14.5\text{A}, di/dt = 100\text{A}/\mu\text{s}$			45	ns
Q_{rr}	Reverse Recovery Charge	$I_F = 14.5\text{A}, di/dt = 100\text{A}/\mu\text{s}$			34	nC

Notes:

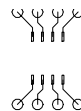
1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50 $^\circ\text{C}/\text{W}$ (10 sec) when mounted on a 1 in² pad of 2 oz copper



b) 105 $^\circ\text{C}/\text{W}$ when mounted on a .04 in² pad of 2 oz copper



c) 125 $^\circ\text{C}/\text{W}$ when mounted on a minimum pad

Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%.

3: The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

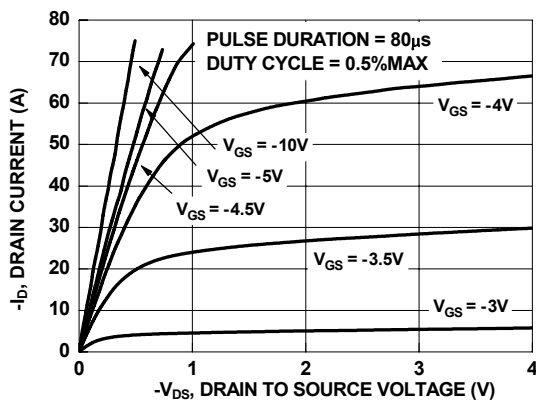


Figure 1. On Region Characteristics

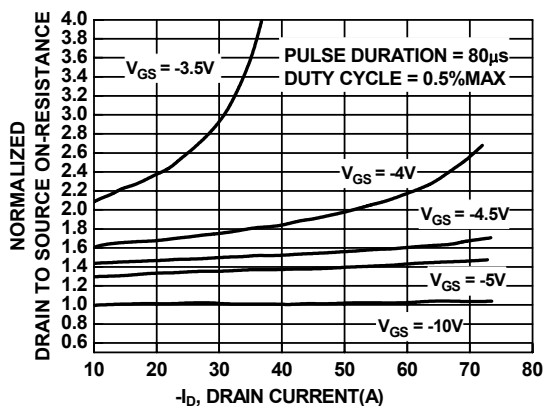


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

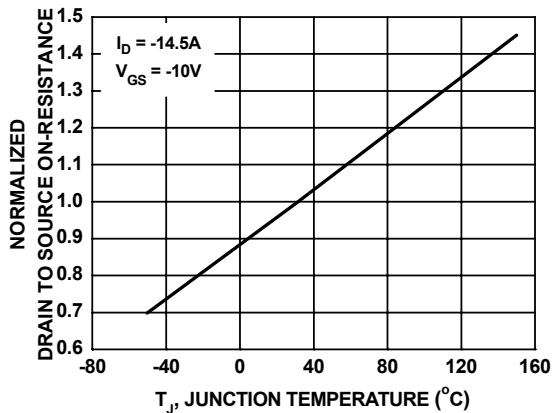


Figure 3. Normalized On Resistance vs Junction Temperature

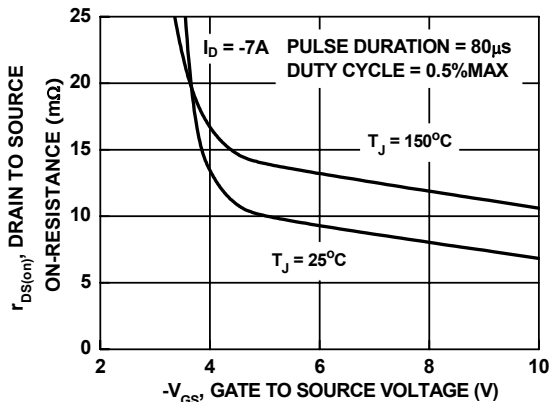


Figure 4. On-Resistance vs Gate to Source Voltage

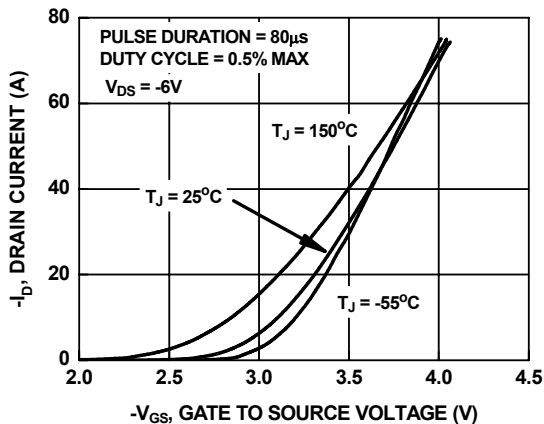


Figure 5. Transfer Characteristics

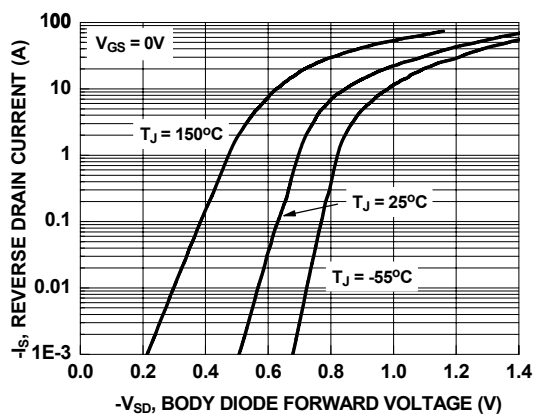


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

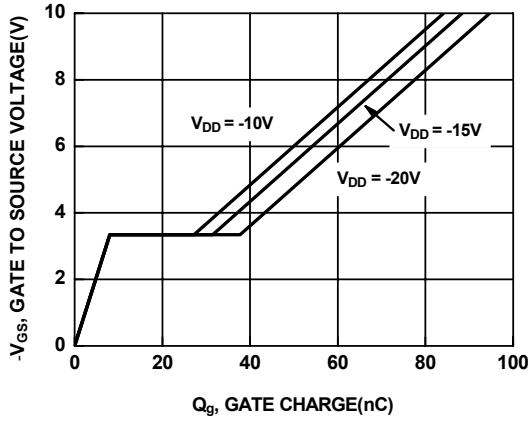


Figure 7. Gate Charge Characteristics

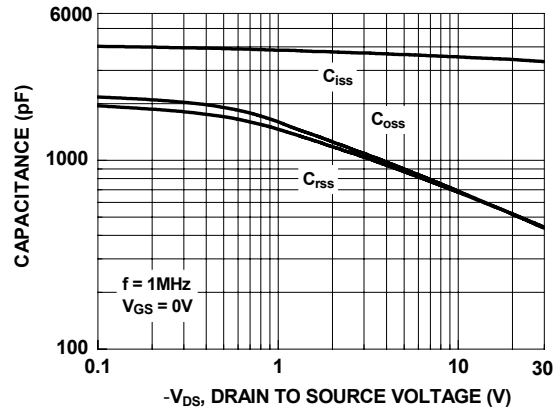


Figure 8. Capacitance vs Drain to Source Voltage

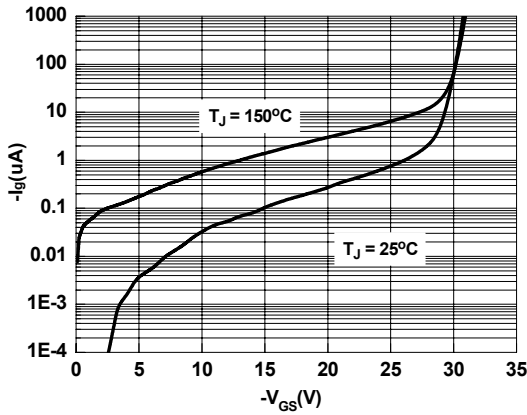


Figure 9. I_g vs V_{GS}

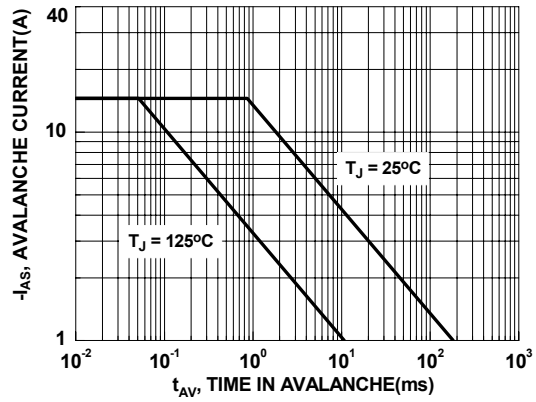


Figure 10. Unclamped Inductive Switching Capability

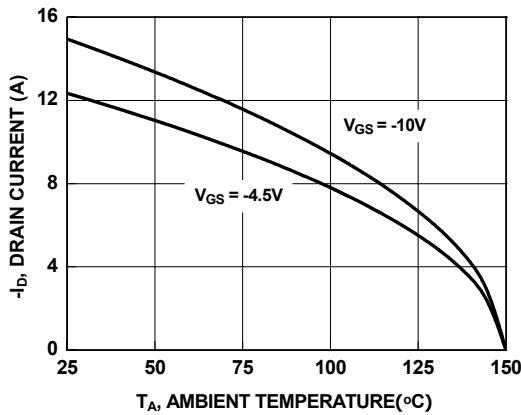


Figure 11. Maximum Continuous Drain Current vs Ambient Temperature

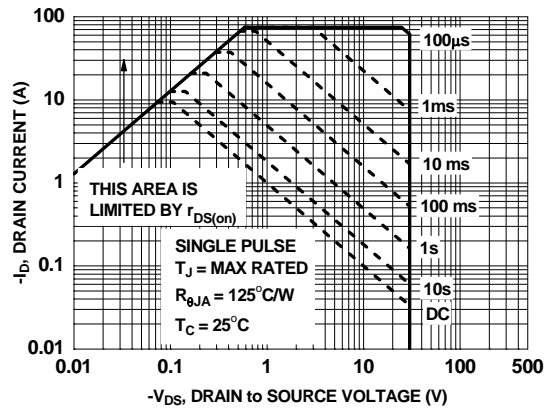


Figure 12. Forward Bias Safe Operating Area

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

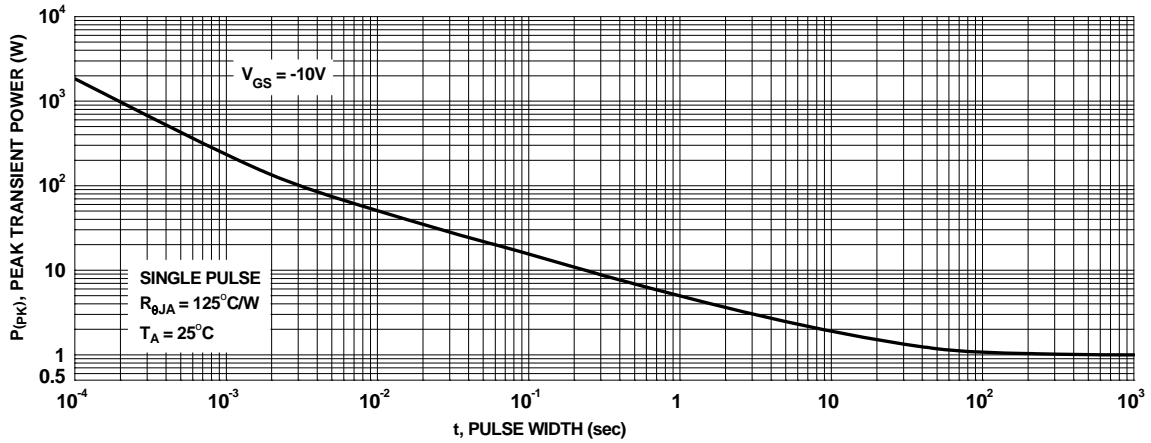


Figure 13. Junction-to-Case Transient Thermal Response Curve

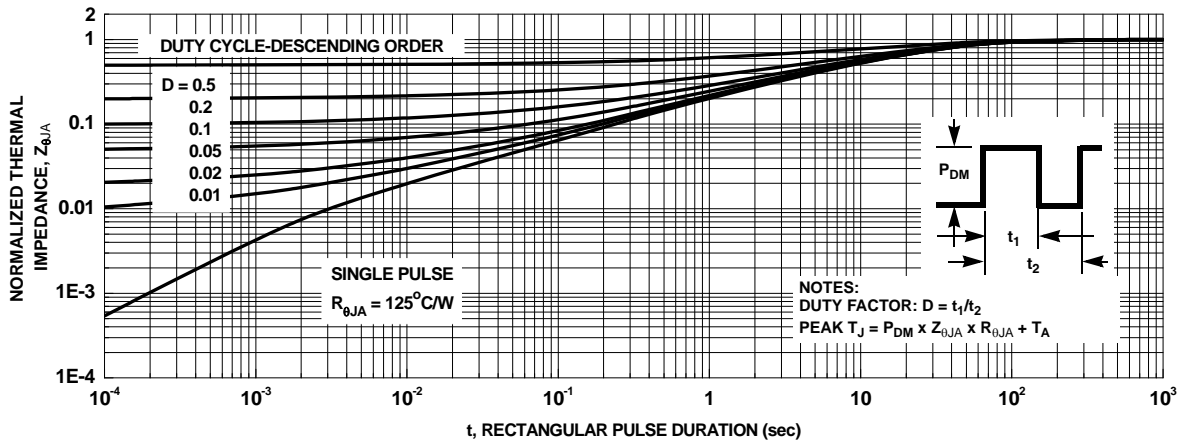








Figure 14. Junction-to-Ambient Transient Thermal Response Curve



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|---|---|---|---|
| Auto-SPM™ | F-PFST™ | PowerTrench® | The Power Franchise® |
| Build it Now™ | FRFET® | PowerXS™ | the power® |
| CorePLUS™ | Global Power Resource SM | Programmable Active Droop™ | franchise |
| CorePOWER™ | Green FPS™ | QFET® | TinyBoost™ |
| CROSSVOLT™ | Green FPS™ e-Series™ | QS™ | TinyBuck™ |
| CTL™ | Gmax™ | Quiet Series™ | TinyLogic® |
| Current Transfer Logic™ | GTO™ | RapidConfigure™ | TINYOPTO™ |
| EcoSPARK® | IntelliMAX™ |  ™ | TinyPower™ |
| EfficientMax™ | ISOPLANAR™ | Saving our world, 1mW /W /kW at a time™ | TinyPWM™ |
| EZSWITCH™ *
™** | MegaBuck™ | SmartMax™ | TinyWire™ |
|  | MICROCOUPLER™ | SMART START™ | TriFault Detect™ |
|  | MicroFET™ | SPM® | TRUECURRENT™* |
| Fairchild® | MicroPak™ | STEALTH™ | µSerDes™ |
| Fairchild Semiconductor® | MillerDrive™ | SuperFET™ |  |
| FACT Quiet Series™ | MotionMax™ | SuperSOT™-3 | UHC® |
| FACT® | Motion-SPM™ | SuperSOT™-6 | Ultra FRFET™ |
| FAST® | OPTOLOGIC® | SuperSOT™-8 | UniFET™ |
| FastvCore™ | OPTOPLANAR®
® | SupreMOS™ | VCX™ |
| FETBench™ |  | SyncFET™ | VisualMax™ |
| FlashWriter®*
FPS™ | PDP SPM™ | Sync-Lock™ | XS™ |
| | Power-SPM™ |  | |

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 140